

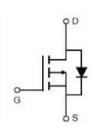
MJ P-Channel Enhancement Mode Power MOSFET

Description

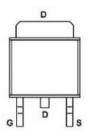
The MJ60P16AK uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. This device is well suited for use as a load switch or in PWM applications.

General Features

- $ightharpoonup V_{DS} = -60 \text{V}, I_D = -16 \text{A}$ $R_{DS(ON)} < 65 \text{m}\Omega$ @ V_{GS}=-10 V $R_{DS(ON)} < 85 \text{m}\Omega$ @ V_{GS}=-4.5 V
- ◆ High density cell design for ultra low Rdson
- ◆ Fully characterized avalanche voltage and current
- ◆ Excellent package for good heat dissipation





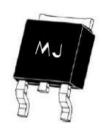


Application

Load switch

PWM application

Marking and pin assignment



TO-252-2L top view

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ60P16AK	MJ60P16AK	TO-252-2L	ä	=	-

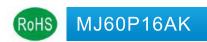
Absolute Maximum Ratings (Tc =25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vps	-60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lD	-16	А
Pulsed Drain Current	Ідм	-64	А
Maximum Power Dissipation	Po	32	W
Derating factor		0.21	W/°C
Single pulse avalanche energy (Note 5)	Eas	65	mJ
Operating Junction and Storage Temperature Range	TJ ,Tstg	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rөjc	4.68	°C/W	
---	------	------	------	--





Electrical Characteristics (Tc =25°Cunless otherwise noted)

Drain-Source Breakdown Voltage BVDSS Vos=0V Io=−250µA -60 - V Zero Gate Voltage Drain Current Ioss Vos=−80V Vos=0V - - - 1 µA Gate-Body Leakage Current Ioss Vos=−250µ Vos=0V - - - 1 µA Calle-Body Leakage Current Ioss Vos=20V Vos=0V - - 1 100	Parameter	Symbol	Condition	Min	Тур	Max	Unit
Zero Gate Voltage Drain Current 1055	Off Characteristics	'	1	1			
Gate-Body Leakage Current Ioss Vos=±20V,Vos=50V - - ±100 nA	Drain-Source Breakdown Voltage	BVpss	V _{GS} =0V I _D =-250μA	-60	-	_	V
On Characteristics (Notes 1)	Zero Gate Voltage Drain Current	IDSS	V _{DS} =-60V,V _{GS} =0V	-	-	-1	μA
Vos Vos	Gate-Body Leakage Current	Igss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
Drain-Source On-State Resistance Ros(αν) Vos=-10V, Io=-8A - 55 65 mC.	On Characteristics (Note 3)						
Prain-Source On-State Resistance Resions Ves=-4.5V, lo=-8A - 65 85 mΩ	Gate Threshold Voltage	VGS(th)	Vps=Vgs ,Ip=-250μA	-1.0	-1.5	-2.0	V
Vos=-4.5V, D=-8A - 65 85 mC.	Davis Course On Otata Basistana		V _{GS} =-10V, I _D =-8A	-	55	65	mΩ
Dynamic Characteristics Notate 4	Drain-Source On-State Resistance	KDS(ON)	V _{GS} =-4.5V, I _D =-8A	-	65	85	mΩ
Input Capacitance	Forward Transconductance	grs	V _{DS} =-5V,I _D =-8A	-	15	-	S
Output Capacitance Coss Vos=-30V,Vos=0V F=1.0MHz - 73.7 - PF	Dynamic Characteristics (Note 4)						
F = 1.0MHz F	Input Capacitance	Clss		-	1108	-	PF
Switching Characteristics (Note 4) Turn-on Delay Time to (Incompose the property of t	Output Capacitance	Coss		-	73.7	-	PF
Turn-on Delay Time tol(on) - 8 - nS Turn-on Rise Time tr Vope-30V, Rt=3.75Ω Vos=-10V, Ro=3Ω - 4 - nS Turn-Off Delay Time tr - - 32 - nS Turn-Off Fall Time tr - - - - - nS Total Gate Charge Qg Vos=-30V, Ib=-8A Vos=-10V - - - nC Gate-Source Charge Qgs Vos=-30V, Ib=-8A Vos=-10V - - - nC Gate-Drain Charge Qgd - - - - - nC Drain-Source Diode Characteristics VSD Vos=0V, Is=-16A - <td>Reverse Transfer Capacitance</td> <td>Crss</td> <td></td> <td>-</td> <td>58.2</td> <td>-</td> <td>PF</td>	Reverse Transfer Capacitance	Crss		-	58.2	-	PF
Turn-on Rise Time t V _{DD} =-30V, R _L =3.75Ω V _{SS} =-10V,RG=3Ω - 4 - nS Turn-Off Delay Time t _d (off) - 32 - nS Turn-Off Fall Time tr - 7 - nS Total Gate Charge Q _g - 23.4 - nC Gate-Source Charge Q _g V _{DS} =-30V,I _D =-8A V _{GS} =-10V - 4.1 - nC Gate-Drain Charge Q _g d - 4.8 - nC Drain-Source Diode Characteristics V _{SD} V _{GS} =0V,I _S =-16A - - -1.2 V Diode Forward Voltage (Note 3) V _{SD} V _{GS} =0V,I _S =-16A - - -1.2 V Diode Forward Current (Note 2) Is - - - - - nS di/dt=-100A/µ _S (Note 3) T _J =25°C, I _F =-8A di/dt=-100A/µ _S (Note 3) - - - - - - - - - - - - - - <t< td=""><td>Switching Characteristics (Note 4)</td><td></td><td></td><td></td><td></td><td></td><td></td></t<>	Switching Characteristics (Note 4)						
Turn-Off Delay Time td(off) Vos=-30V, R _L =3.75Ω Vos=-10V, R _G =3Ω - 32 - nS	Turn-on Delay Time	t _{d(on)}		-	8	_	nS
Turn-Off Delay Time to VGS=-10V,RG=3Ω - 32 - nS	Turn-on Rise Time	tr	Vpp=-30V Rt=3 750	_	4	-	nS
Total Gate Charge Qg	Turn-Off Delay Time	t _{d(off)}		-	32	-	nS
Gate-Source Charge Qgs Vbs=-30V,lb=-8A Vcs=-10V - 4.1 - nC	Turn-Off Fall Time	tr		-	7	_	nS
Gate-Source Charge Ggs Ves=-10V - 4.1 - Inc	Total Gate Charge	Qg		-	23.4	-	nC
Qgd	Gate-Source Charge	Qgs		-	4.1	-	nC
Diode Forward Voltage (Note 3) VSD Vos=0V,Is=-16A - - -1.2 V Diode Forward Current (Note 2) Is - - -16 A Reverse Recovery Time trr TJ=25°C, IF=-8A di/dt=-100A/µs (Note 3) - 25 - nS	Gate-Drain Charge	Qgd	-	-	4.8	_	nC
Diode Forward Current (Note 2) Is 16 A	Drain-Source Diode Characteristics					<u> </u>	
Reverse Recovery Time	Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =-16A	-	_	-1.2	V
di/dt=-100A/µs (Note 3)	Diode Forward Current (Note 2)	ls		-	-	-16	А
di/dt=-100A/µs (Note 3)	Reverse Recovery Time	trr	T1=25°C Ir- 9^	_	25	_	nS
	Reverse Recovery Charge	Qrr	di/dt=-100A/µs (Note 3)	_	31	_	nC

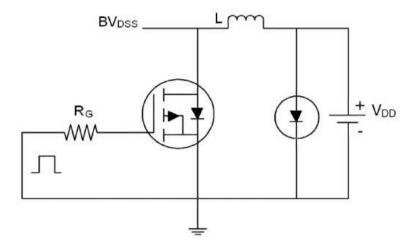
Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3 Pulse Test; Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2\%$.
- 4 Guaranteed by design, not subject to production

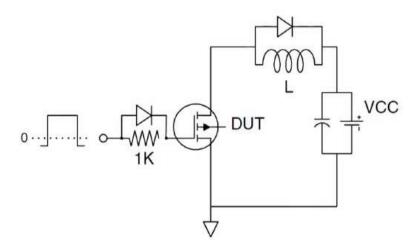




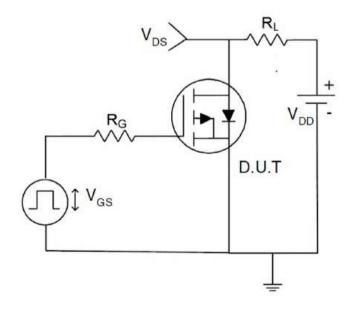
Test circuit



Eas test Circuit



Gate charge test Circuit

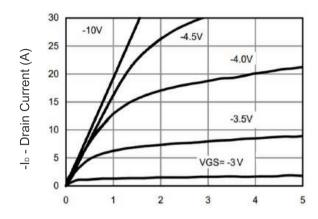


Switch Time Test Circuit



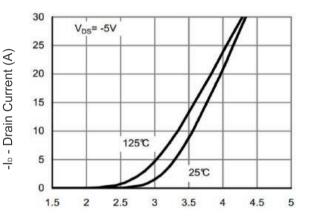


Typical Electrical and Thermal Characteristics (Curves)



-Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



-Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

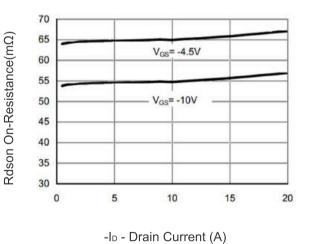
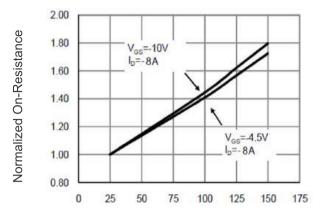
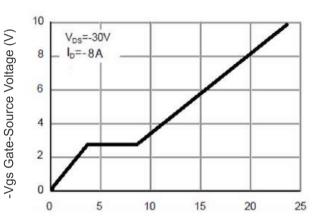


Figure 3 Rdson- Drain Current



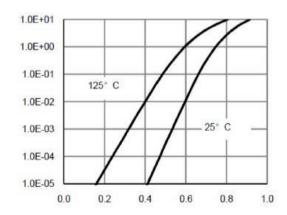
T_J -Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)

Figure 5 Gate Charge



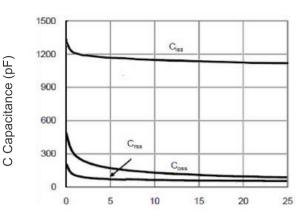
-Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward

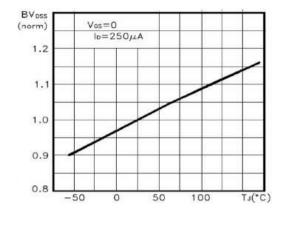
-Is - Reverse Drain Current (A)



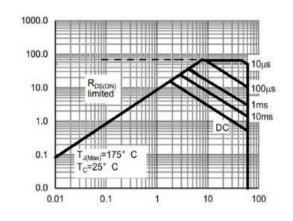
-l_o - Drain Current (A)



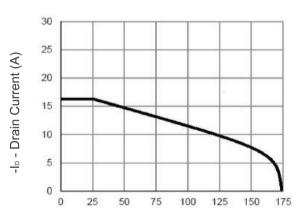
-Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



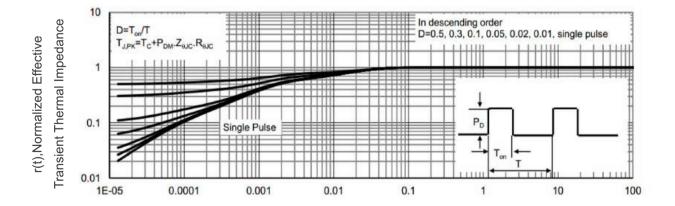
T₃-Junction Temperature(°C)
Figure 9 BVpss vs Junction Temperature



-Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



T_J -Junction Temperature(°C)
Figure 10 I_D Current De-rating



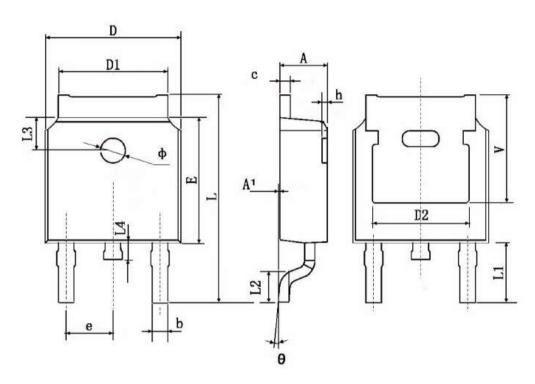
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance





TO-252 Package Information



Complete	Dimensions	n Millimeters	Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
Α	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
С	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.8	30 TYP.	0.190	TYP.
E	6.000	6.200	0.236	0.244
е	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600	TYP.	0.063	TYP.
L4	0.600	1.000	0.024	0.039
Ф	1.100	1.300	0.043	0.051
θ	0°	8°	0.	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211	TYP.





Attention:

Any and all MJ power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MJ power representative nearest you before using any MJ power products described or contained herein in such applications.

MJ power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MJ power products described or contained herein.

Specifications of any and all MJ power products described or contained herein stipulate the erformance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

MJ power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all MJ power products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or therwise, without the prior written permission of MJ power Semiconductor CO.,LTD.

Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MJ power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MJ power product that you intend to use.

This catalog provides information as of Sep.2010. Specifications and information herein are subject to change without notice.